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DATE: February 6, 2006
FILE NO: APPM/008241/PPC/ECP/CKIM
TO: Commissioner for Patents
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FROM: Keith M. Tackett
PAGE(S) with cover: 3
ORIGINAL TO FOLLOW? ☐ YES ☒ NO

NOTICE OF APPEAL AND PETITION FOR 1-MONTH EXTENSION OF TIME

TITLE: Multiple-Step Electrodeposition Process for Direct Copper Plating on Barrier Layers
U.S. SERIAL NO.: 10/616,097
FILING DATE: July 8, 2003
INVENTOR: Sun, et al.
EXAMINER: Edna Wong
GROUP ART UNIT: 1753
CONFIRMATION NO.: 1645

CONFIDENTIALITY NOTE

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